

04DO #2 0420

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
BUR920010071US1

In Re Application Of **IBM Corp., et al.**

Serial No.
09/682,957

Filing Date
Nov. 2, 2001

Examiner
not known

Group Art Unit
not known

Title: **TRANSISTOR STRUCTURE WITH THICK RECESSED SOURCE/DRAIN STRUCTURES
AND FABRICATION PROCESS OF SAME**

Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

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Melinda Meyer

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Mark F. Chadurjian
Signature

Mark F. Chadurjian, Reg. No. 30,739

IBM CORPORATION
Intellectual Property Law - Zip 972E
1000 River Street
Essex Junction, Vermont 05452

Dated: **11/05/2001**

CC:

#2

INFORMATION DISCLOSURE STATEMENT PURSUANT TO
37 C.F.R. §§1.97-1.99

PATENT APPLICATION

Applicant(s): Bryant, et al.

Docket No. BUR920010071US1

FOR: **TRANSISTOR STRUCTURE
WITH THICK RECESSED
SOURCE/DRAIN STRUCTURES
AND FABRICATION PROCESS
OF SAME**

Commissioner for Patents
Box Patent Application
Washington, D.C. 20231

Sir:

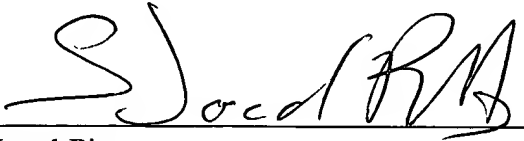
In accordance with the duty of disclosure under 37 C.F.R. §1.56 and pursuant to 37 C.F.R. §§1.97-1.99, Applicant(s) hereby notifies the U.S. Patent and Trademark Office of the documents listed on the attached Form PTO-1449. One copy of each cited document is submitted herewith. Applicant respectfully submits that all pending claims are patentable over the foregoing references, alone or in combination. The Examiner is requested to initial the enclosed Form PTO-1449 and return a copy thereof to the undersigned.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant reserves the right to dispute any of the listed documents as prior art during examination. Further, Applicant does not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application. Furthermore, the submission of this Information Disclosure

Statement is not to be construed as a representation that a search has been made or that no other material information may exist.

This Information Disclosure Statement is being filed within three months of the filing date of the captioned patent application, and therefore no certification under 37 C.F.R. §1.97(e) or fee under 37 C.F.R. §1.17(p) is required.

Respectfully submitted,

By 
S. Jared Pitts
Reg. No.:38,579

Date: October 8, 2001

Enclosures: PTO-1449
Patent copies

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
BUR920010071US1

In Re Application Of **Bryant, et al.**

Serial No.
09/682,957

Filing Date
Nov. 2, 2001

Examiner
not known

Group Art Unit
not known

Title: **TRANSISTOR STRUCTURE WITH THICK RECESSED SOURCE/DRAIN STRUCTURES
AND FABRICATION PROCESS OF SAME**

Address to:
**Assistant Commissioner for Patents
Washington, D.C. 20231**

37 CFR 1.97(b)

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application; within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or before the mailing date of a first Office Action on the merits, whichever event occurs last.

37 CFR 1.97(c)

2. ☐ The Information Disclosure Statement submitted herewith is being filed after three months of the filing of a national application, or the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or after the mailing date of a first Office Action on the merits, whichever occurred last but before the mailing date of either:

1. a Final Action under 37 CFR 1.113, or
2. a Notice of Allowance under 37 CFR 1.311,

whichever occurs first.

Also submitted herewith is:

- ☐ a certification as specified in 37 CFR 1.97(e);

OR

- ☐ the fee set forth in 37 CFR 1.17(p) for submission of an Information Disclosure Statement under 37 CFR 1.97(c).